

□	! " #□	\$! % & ' □	! () % * + □	, - □	. / □
□	□	□	□	□	□
□	□	□	0 1 2 3 4 5 6 7 8 □	9 : □	; < = □
□	□	□	> ? @ A B C D B C D □ E F G H I J K L H □	M N O □	P Q R □
□	□	□	最大值 改为 波峰焊改为回 流焊	9 : □	M N O □
□	□	□	STU □	9 : □	M N O □
□	, □ □	VW X , Y Z > [U			

/ Descriptions

Y Y Z] ^ _ ` a b c

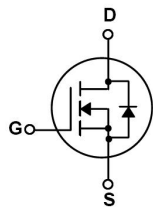
/ Features

d e f g d h i f + j K k l m n 5 6 o p c
r d .

/ Applications

q r s t u v w x t u j K c

/ Equivalent Circuit



/ Pinning



y y y y

/ Marking

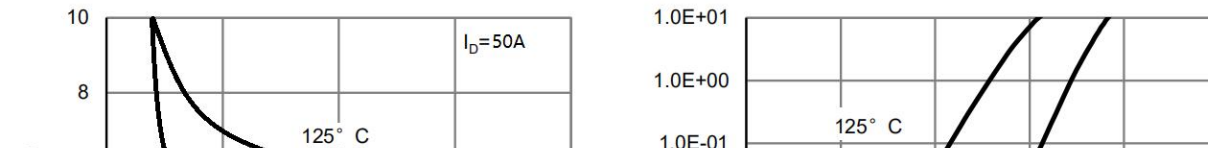
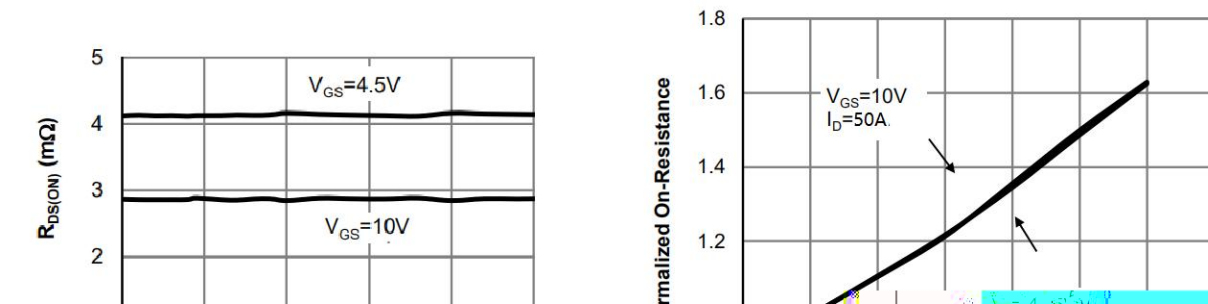
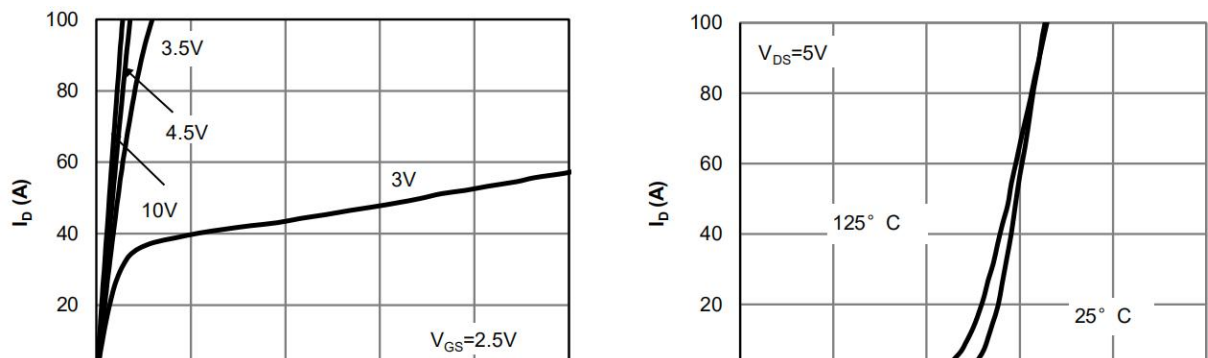
z { | } ~ c

参数	符号	数值	单位
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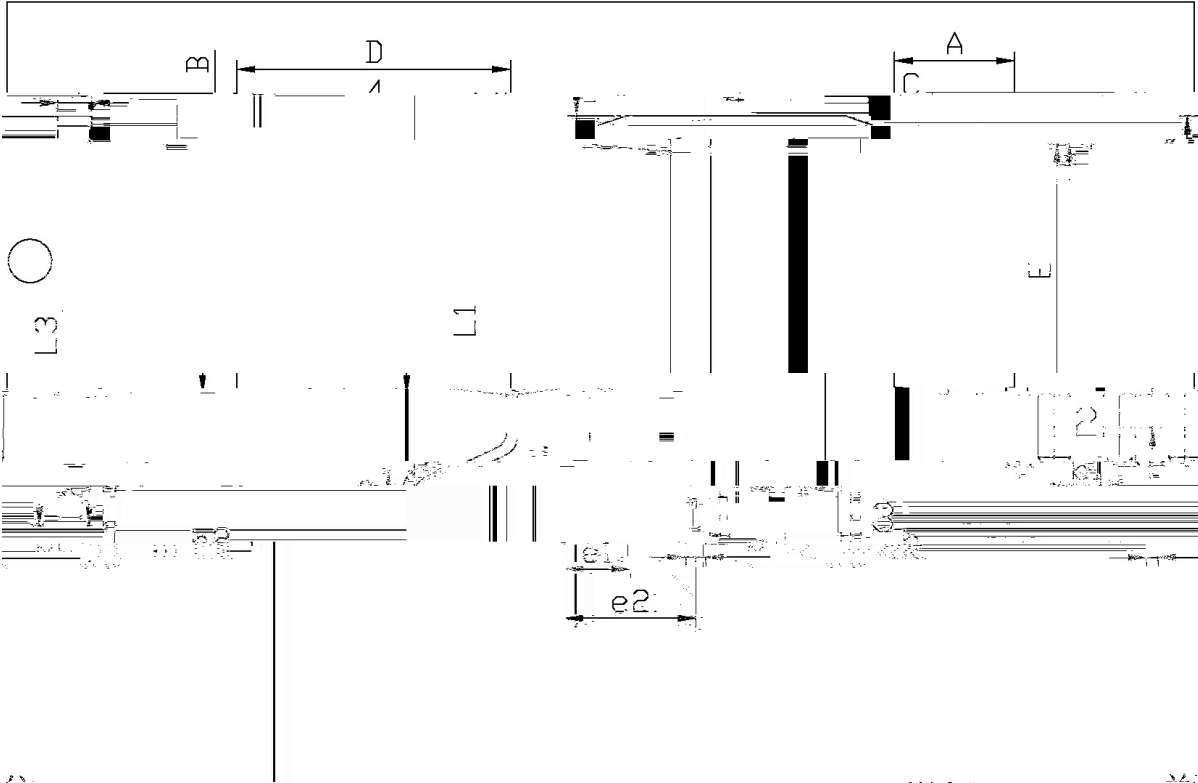
/ Electrical Characteristics(Ta=25)

参数	符号	测试条件	最小值	典型值	最大值	单位

/ Electrical Characteristic Curve

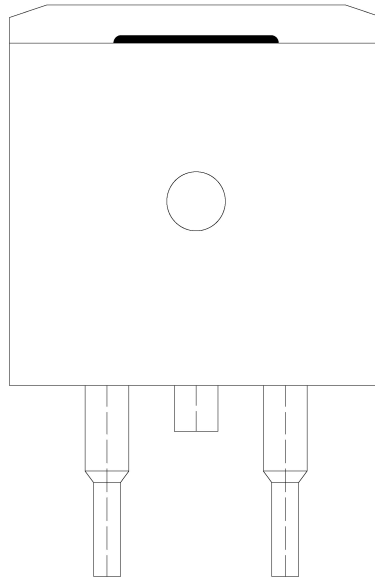


/ Package Dimensions



単位: mm									
Dimensions in Millimeters									
		Min		Max		Min		Max	
A		4.30		4.70		E		9.00	
B		16.00		1.40		e1		2.34	
C		0.70		0.90		e2		0.11	
15	U35 (L1)	L1	15.00	16.00				b1	11
40	U60 (L2)	L2	2.24	2.84				b2	0.
20	U40 (L3)	L3	1.20	1.60				c	1.
D		9.80		10.20					
T□-263									

/ Marking Instructions



100N03

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

±

°C

±

°C

±

°C

±

°C

/ Resistance to Soldering Heat Test Conditions

±

°C

±

°C

°C

/ Packaging SPEC.